

BSTCM24C256S 256K bit I2C Bus Serial EEPROM MANUAL

1. Product Overview

BSTCM24C256S Type 256K bit I2C Bus Serial EEPROM, is a CMOS The monolithic integrated circuits manufactured by the process mainly provide 256K bit Serial Electrically Erasable Programmable Read-Only Memory (EEPRO M), I 2 C interface, the memory structure is 32768×8bit, internally divided into 512 pages per page 64 bytes.

1.1. Features:

- Operating voltage (V CC): 2.5V~5.5V
- Quiescent current (ISB): ≤5.0µA
- Input leakage current (I LI): ≤2.0 μA
- Output low level voltage (V OL): ≤ 0.4V (@ I O- =+3.0mA, V CC = 5.0V)
- $\leq 0.2 \text{V}$ (@ I O- = +1.0mA, V CC =2.5V)
- Working temperature (TA): -55 °C ~ 105 °C
- Packaging type: plastic packaging SOP8

1.2. Application:

General purpose product, mainly used for ground equipment.

2. Package and pin description

Bonding area pin description and coordinates:



Table 1. Pin Description

Pin number	Symbol	I/O	Achievement able	
1	E0	I	enter	
2	E1	I	enter	
3	E2	I	enter	
4	GND	Р	land	
5	SDA	I	enter	
<u> </u>	SCL	I	enter	
7	WP	I	enter	
8	VCC	P	power supply	

Port Description:

Typically, E2, E1 and E0 The pins are used for hardware addressing. A total of 8 If these pins are left floating, the E2, E1, and E0 pins will be internally pulled down to GND.

SDA pin is a bidirectional port for data transmission. This pin is open-drain driven and can perform wired-OR logic operations with any number of other open-drain or open-collector devices.

III. Absolute Maximum Ratings

Power supply voltage (V CC) V~6.25V

Maximum power consumption (PD) 100mW

Storage temperature range (Tstg) - 65 °C ~ 150 °C

Maximum junction temperature (T j) 175 °C

IV. Recommended operating conditions

Power supply voltage (V CC) V~5.5V

Operating ambient temperature (TA) - 55 °C~ 105 °C



V. Technical indicators

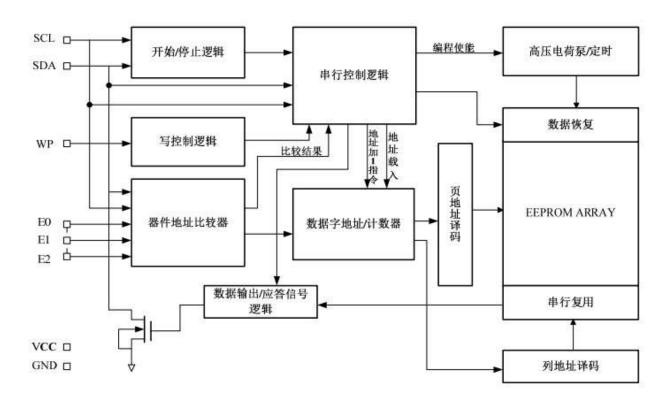
Table 1. Electrical parameter characteristics (circuit)

	Table 1. Electrical parameter characterist			· ' '			l
		Condition Unless otherwise specified, - 55 °C ≤ T A ≤ 125		Limit value			1.1
Parameter name	Symbol	specified, - 55 °C ≤ T	A≥ 125	Minimum	Typical	Maximum	Unit
Quiescent Current	I SB	V cc =5.5V/3.3V, /E0/E1/E2=000, SCL=SDA=1, WP=0		_	<1	5.0	μΑ
Input high level voltage	VI	VCC = 5V		0.7 V cc	_	_	V
Input low level voltage	VIL	VCC = 5V		_	_	0.3 V cc	V
Input leakage current	I LI	VCC = 5.5V, VIN = VCC / GND SCL, SDA, WP		_	<0.1	2.0	μΑ
Output low level		$I_{O-} = +3.0$ mA, $V_{CC} = 5.0$ V		_	_	0.4	V
voltage		I o- = +1.0mA, V cc = 2.5V		_	_	0.2	V
	I CCR	V cc =5.5V, f =400kHz,	Read Operation	_	_	0.6	mA
Working current	I CCW	SDA Connect 2KΩ pull - up resistor	Write Operation	_	_	2.0	mA
Clock Pulse Width Low	t LOW			0.6	_	_	μs
High	t HIGH			0.6	_	_	μs
Before transmitting the next value bus The time at which the bus must be released	t BUF			0.6		_	μs
Start condition hold time	t HD.S T A			0.3		_	μs
Start condition setup time	t SU.S T A	V cc =2.5V/5.0V, see figure 3		0.3		_	μs
Data input hold time	t HD.DAT			0.1	_	_	μs
Data input setup time	tSU.DAT			0.2	_	_	μs
Stop condition setup time	tSU.STO			0.4	_	_	μs
WP Build Time	tSU.WP			1.0	_	_	μs
WP Keep Time	t HD.WP	V cc =2.5V/5.0V		1.0		_	μs



		V $_{CC}$ = 2.5V, write the entire device 00~FF rolling code, FF~00 Rolling code, 00, FF			
Functional testing	_	And read out verification V $_{\text{CC}}$ = 5.5V, write the entire device 00, FF And read out verification		_	
Note: Voltage is based on GND As the benchmark, GND=0, the currentng into the chip terminal is flowi positive.					

VI. Functional Description



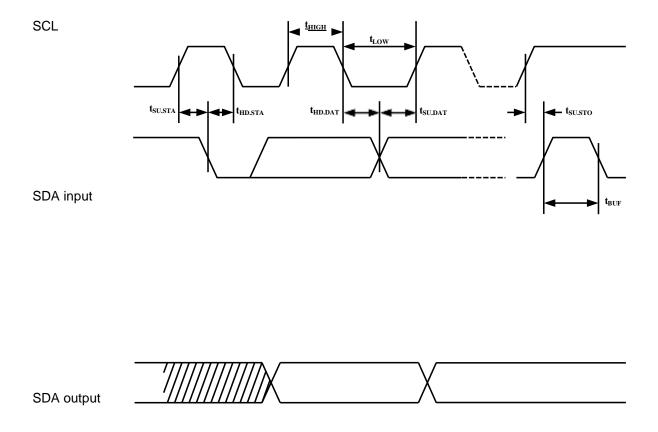
Picture 2. Functional Block Diagram

This circuit mainly provides 256K bit Serial electrically erasable programmable read-only memory (EEPRO M),I 2 C interface, the memory structure is 32768 × 8bit, internally divided into 512 pages per page 64 bytes.

VII. Application Notes

Typical application diagram:





Picture 3. Switching timing diagram

VIII. Precautions for use:

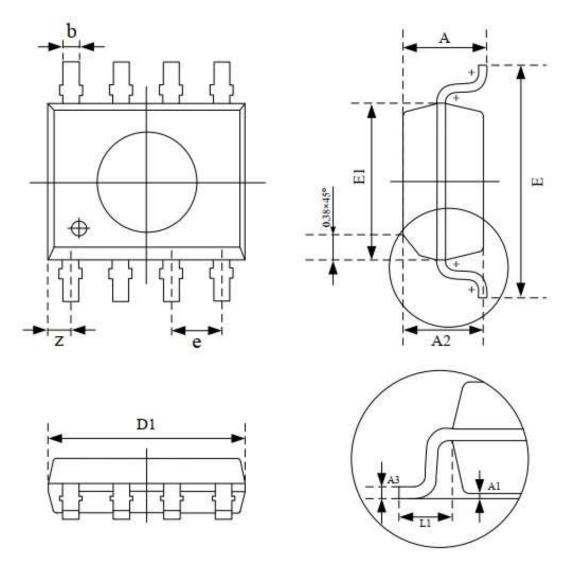
- This product is CMOS Circuits are electrostatically sensitive devices, so you
 should pay attention to anti- static when using and storing them. When welding, it
 is especially important to wear an anti-static wristband. Otherwise, it is very easy
 to cause damage to the device.
 - It is strictly forbidden to ground the output.
- Usually, E2, E1 and E0 The pins are used for hardware addressing. A total of If
 these pins are left floating, E2, E1 and E0 The pin will be internally pulled down to
 GND. SDA The pin is a bidirectional port for data transmission. This pin is
 opendrain driven and can perform wired-OR logic operations with any number of
 other open-drain or open-collector devices.
- When using, try to ensure that the circuit works under the recommended working conditions. If the circuit works above the absolute maximum rating, it is very easy to cause device damage and lead to device failure.



In order to reduce the interference on the power supply, it is recommended to add $0.1\mu F$ to V CC -GND near the chip. Capacitance.

IX. Dimensions

This circuit uses 8 Lead plastic package (SOP8) package, the dimensions are as shown in the figure 4 regulations.



Picture 4. Dimensions

Unit is mm



Dimension symbols	Numeric				
	Most Small	Male say	Most big		
A	1.500	<u> </u>	1.700		
A1	0.100	_	0.200		
A2 b	_	1.450	_		
A3 b	_	0.223	_		
b c	0.356	-	0.486		
e b	_	1.270	_		
D1 a	4.790	-	4.930		
E	5,900	-	6.100		
E1 a	3.810	-	3.960		
L1 b	0.950	-	1.150		
Z	_	0.535			

X. Disclaimer

- Our institute is only responsible for the current validity of this product manual when it is issued, and no separate notice will be given for version updates.
- All technical information contained in this product manual is only for users to have a preliminary understanding of this product. If there is any discrepancy with the detailed product specifications, the detailed product specifications shall prevail.
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